

基板取付穴推奨寸法 (参考) (t=1.6)
RECOMMENDED P.C. BOARD HOLE DIM. (REF.)

注記 NOTES

- 嵌合相手: 51067 シリーズ
MATE WITH: 51067 SERIES
- 材質 MATERIAL
ウエハー: PBTP (ガラス15%入り)、UL94V-0
WAFER: PBTP (G.F 15%), UL94V-0
ピン: リン青銅 ニッケル下地 錫メッキ (t=0.254)
PIN: PHOS. BRO.
TIN OVER NICKEL PLATING (t=0.254)

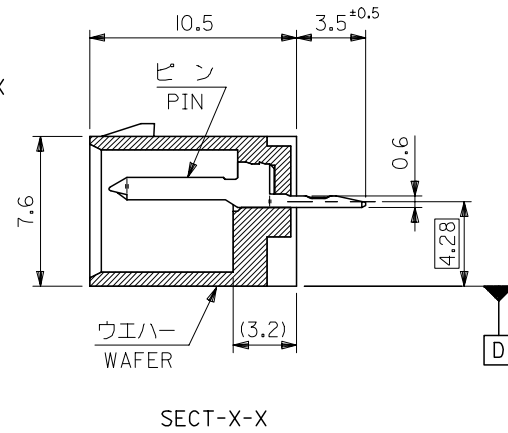
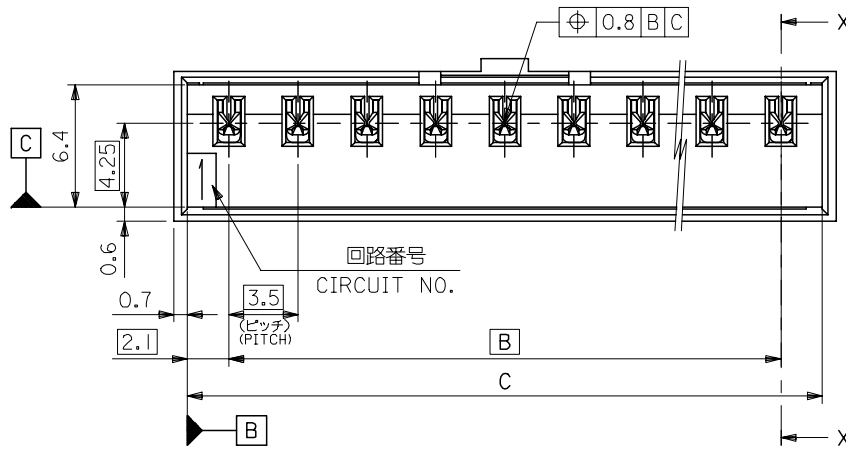
3. MATERIAL NO. の説明
LEGEND

53258-3***

Ver | 極数
色番号 |

0	自然色 (NATURAL)
1	黒 (BLACK)
2	赤 (RED)
3	黄 (YELLOW)
4	青 (BLUE)
5	ピンク (PINK)
6	緑 (GREEN)

4. 本製品は 53258-*** の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53258-***.



8.7	53.2	49.0	54.6	53258-3*15	15
↑	49.7	45.5	51.1	↑ -3*14	14
	46.2	42.0	47.6	↑ -3*13	13
	42.7	38.5	44.1	↑ -3*12	12
	39.2	35.0	40.6	↑ -3*11	11
	35.7	31.5	37.1	↑ -3*10	10
	32.2	28.0	33.6	↑ -3*09	9
	28.7	24.5	30.1	↑ -3*08	8
	25.2	21.0	26.6	↑ -3*07	7
	21.7	17.5	23.1	↑ -3*06	6
↓	18.2	14.0	19.6	↓ -3*05	5
	8.7	14.7	10.5	↓ -3*04	4
	6.1	11.2	7.0	↓ -3*03	3
	6.1	7.7	3.5	↓ 53258-3*02	2
(D)	C	B	A	3. MATERIAL NO.	CKT. 極数

RELEASED EC NO: J2005-1783 DRAWN: NAIDA CHKD: KTOJO APPR: NUKITA 2005/01/07 2005/01/08 2005/01/13	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY N. AIDA	DATE '04/12/16	TITLE 3.5 WIRE TO BOARD CONN WAFER ASSY (ST) -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE '04/12/16	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY N. UKITA	DATE '04/12/16	DOCUMENT NO. SD-53258-008	SHEET NO. 1 OF 1	
	ANGULAR	±3 °	MATERIAL NO. SEE CHART	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							